

The Effect of Wafer Surface Scanner Accuracy on the Determination of Wafer Cleaning Equipment Particles per Wafer Pass

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Abstract

The particles added per wafer pass (PWP) and measurement variability of a wafer surface scanner were investigated to determine their effect on the accuracy of the PWP measurement of semiconductor wafer cleaning equipment. The PWP of the scanner was found to have a minor effect. The variability of the scanner measurement was found to be similar to that of the cleaning equipment. The combined variability of the scanner and the cleaning equipment meant that it was necessary to process large numbers of wafers to accurately determine cleaning equipment PWP.